SMALL-OUTLINE DIODES

'TMPD' General-Purpose and Low-Leakage Diodes

ELECTRICAL CHARACTERISTICS at T_A = 25°C

Device Type	Description	Marking	I_F Max. (mA)	V_{BR} Min. (V)	V_F Max. (V)	V_F @ I_F (mA)	I_R Max. (nA)	t_{rr} Max. (ns)	C_0 Max. (pF)	Process
TMPD459	Low-Leakage	459	500	200	1.0	3.0	25	—	6.0	TRO
TMPD914	General-Purpose	5D	600	100	1.0	10	25	4.0	6.0	TSB
TMPD2835	Common Anode	A3	500	35	1.0	10	0.10	6.0	4.0	DOB
TMPD2836	Common Anode	A2	500	75	1.0	10	0.10	6.0	4.0	DOB
TMPD2837	Common Cathode	A5	500	35	1.0	10	0.10	6.0	4.0	DBA
TMPD2838	Common Cathode	A6	500	75	1.0	10	0.10	6.0	4.0	DBA
TMPD4148	General-Purpose	5D	600	100	1.0	10	25	4.0	4.0	TSB
TMPD4150	General-Purpose	ABA	600	75	0.62	1.0	100	4.0	2.5	TSB
TMPD4153	General-Purpose	AAR	600	75	0.67	1.0	50	4.0	4.0	TSB
TMPD4154	General-Purpose	ABC	600	35	1.0	30	100	4.0	4.0	TSB
TMPD4448	General-Purpose	AAD	600	100	1.0	100	25	4.0	4.0	TSB
TMPD6050	Single Diode	5A	600	70	1.1	100	0.10	10	2.5	TSB
TMPD6100	Common Cathode	5B	500	70	1.1	100	0.10	15	2.5	DBA
TMPD7000	Dual In-Series	5C	600	100	1.1	100	0.30	15	1.5	TSB

'TMPD' Schottky Diodes

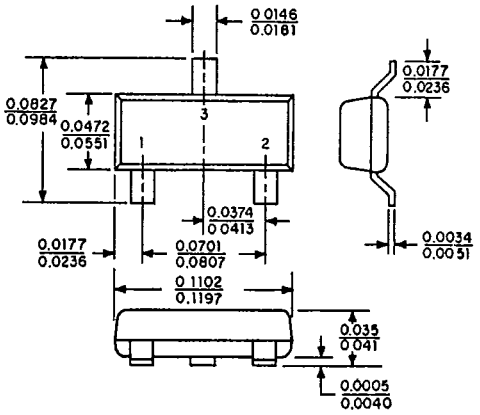
ELECTRICAL CHARACTERISTICS at T_A = 25°C

Device Type	V_{BR} Min. (V)	V_F Max. I_F=1mA (V)	V_F Max. I_F=10mA (V)	I_R Max. V_R=1V (nA)	I_R Max. V_R=20V (nA)	I_R Max. V_R=50V (nA)	C_0 Max. (pF)	Process
TMPD5711	70	0.41	0.75	—	50	200	2.0	BKD
TMPD6916	40	0.34	0.47	100	200	—	5.0	BKA
TMPD6919	50	0.45	0.80	—	200	—	1.2	BKF
TMPD6924	70	0.41	0.75	—	—	200	2.0	BKD

PACKAGE INFORMATION

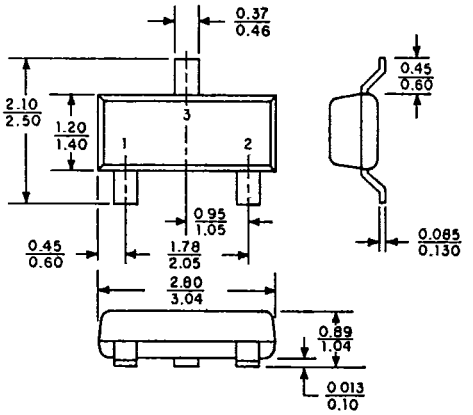
TO-236AB/STYLE CL

DIMENSIONS IN INCHES
Based on 25.4 mm = 1"



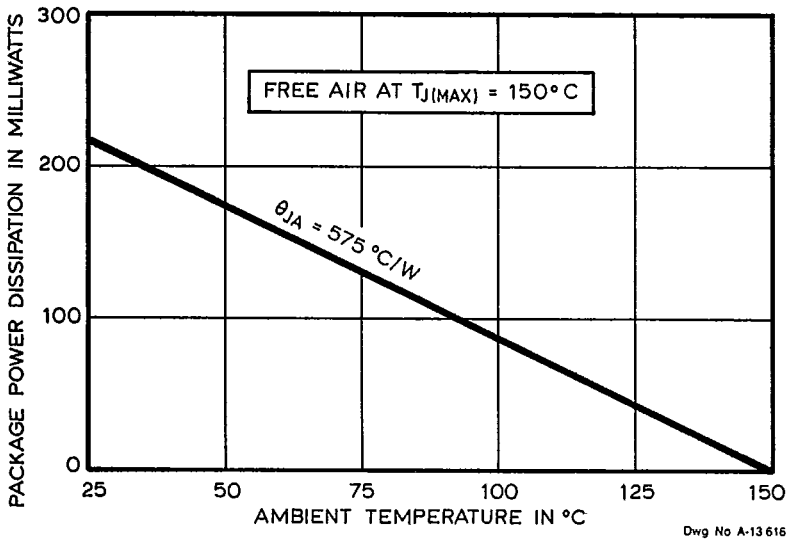
Dwg No. A-12,238B IN

DIMENSIONS IN MILLIMETERS



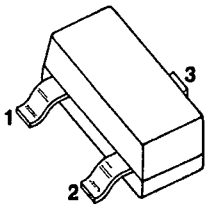
Dwg. No. A-12,238B MM

MAXIMUM ALLOWABLE PACKAGE POWER DISSIPATION AS A FUNCTION OF AMBIENT TEMPERATURE



Dwg No A-13 616

Die size = 0.635 mm by 0.635 mm (0.025" by 0.025"). Other factors that determine allowable package power dissipation in application include circuit board material, pad size, and proximity of other heat producing circuit elements.

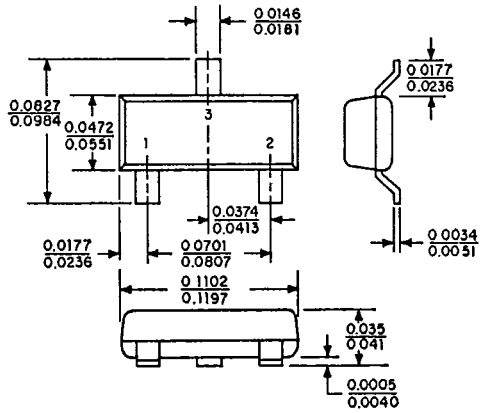


CL PINOUT

Pin	Terminal
1	Anode
2	No Connection
3	Cathode

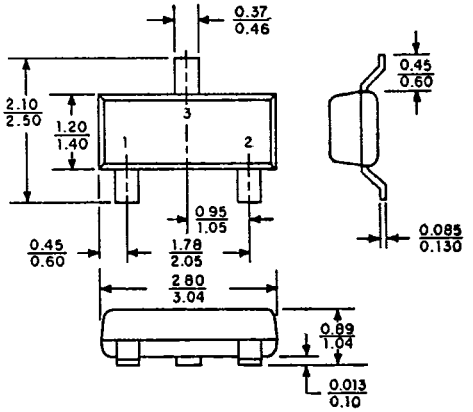
TO-236AB/STYLE CA

DIMENSIONS IN INCHES
Based on 25.4 mm = 1"



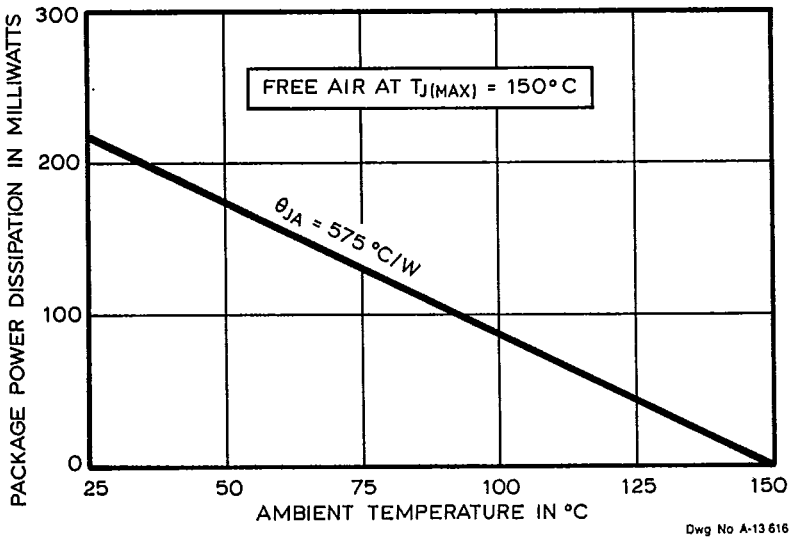
Dwg. No A-12,238B IN

DIMENSIONS IN MILLIMETERS



Dwg. No. A-12,238B MM

MAXIMUM ALLOWABLE PACKAGE POWER DISSIPATION AS A FUNCTION OF AMBIENT TEMPERATURE



Dwg No A-13 616

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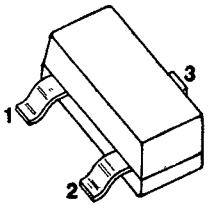


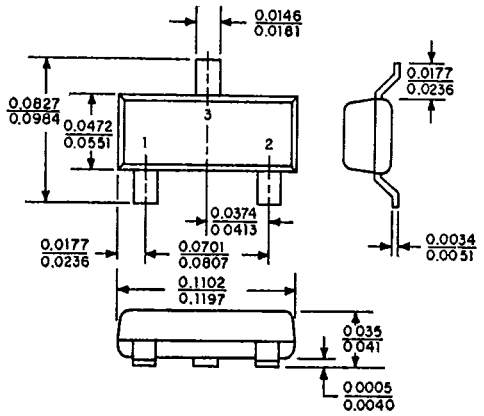
CA PINOUT

Pin	Terminal
1	Anode
2	Anode
3	Cathode

PACKAGE INFORMATION

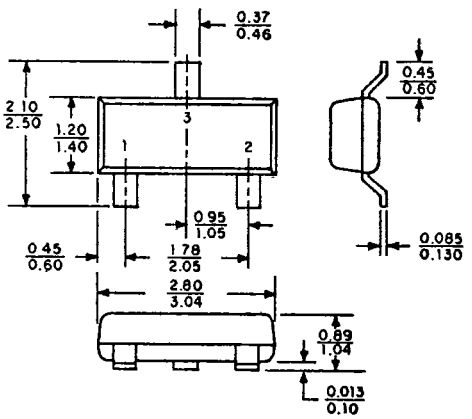
TO-236AB/STYLE CB

DIMENSIONS IN INCHES
Based on 25.4 mm = 1"



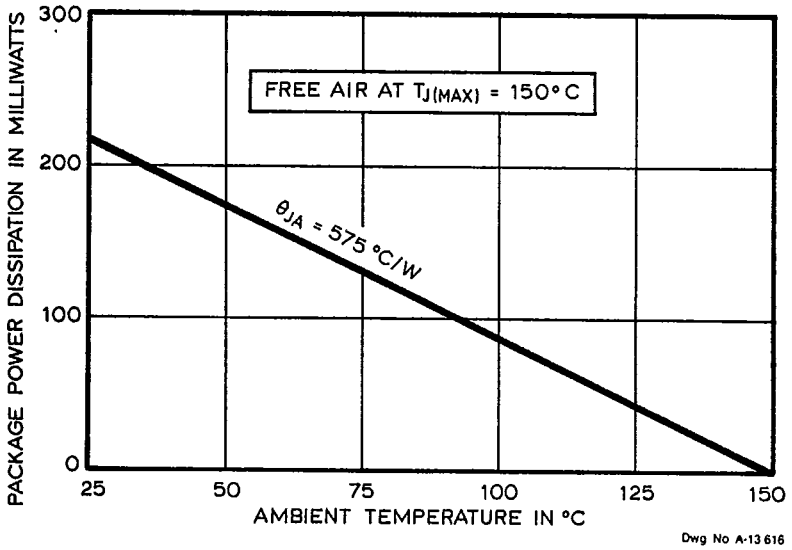
Dwg. No. A-12,238B IN

DIMENSIONS IN MILLIMETERS



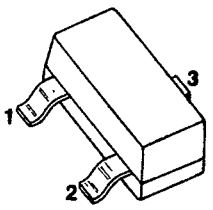
Dwg. No A-12,238B MM

MAXIMUM ALLOWABLE PACKAGE POWER DISSIPATION AS A FUNCTION OF AMBIENT TEMPERATURE



Dwg No A-13 616

Die size = 0.635 mm by 0.635 mm (0.025" by 0.025"). Other factors that determine allowable package power dissipation in application include circuit board material, pad size, and proximity of other heat producing circuit elements.

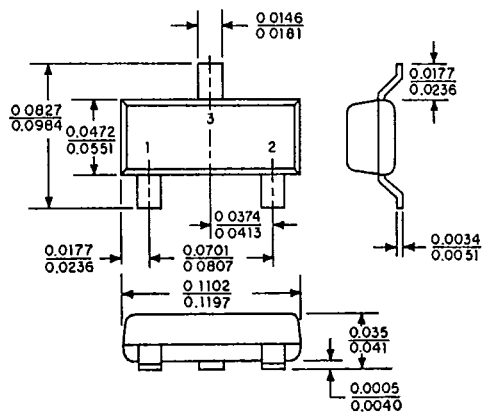


CB PINOUT

Pin	Terminal
1	Anode
2	Cathode
3	Anode and Cathode

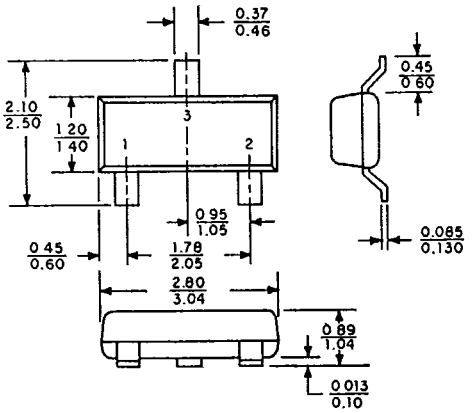
TO-236AB/STYLE CC

DIMENSIONS IN INCHES
Based on 25.4 mm = 1"



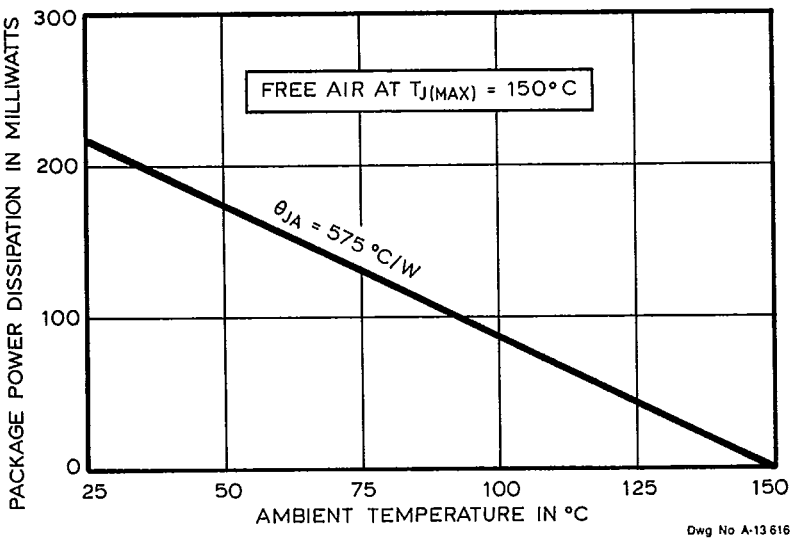
Dwg No A-12,238B IN

DIMENSIONS IN MILLIMETERS



Dwg No. A-12,238B MM

MAXIMUM ALLOWABLE PACKAGE POWER DISSIPATION AS A FUNCTION OF AMBIENT TEMPERATURE



Dwg No A-13 616

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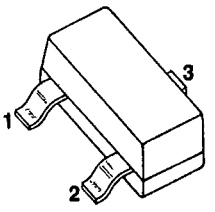

CC PINOUT

Pin	Terminal
1	Cathode
2	Cathode
3	Anode